Serial No. 10/629,106 Preliminary Amendment

REMARKS

Pursuant to the present preliminary amendment, independent claims 1 and 19 have been amended. Claims 1-2, 4-19, 21-23, 26-27, 29-36, 39-43 and 45 are pending in the present application. No new matter has been introduced by way of the present amendment. Reconsideration of the present application is respectfully requested in view of the amendments and arguments set forth herein.

Pursuant to the present amendment, independent claims 1 and 19 have been amended to further define Applicants' invention. More specifically, those claims have been amended to clearly recite that the present invention is directed to performing a first process wherein a layer of material (or metal depending on the claim) is formed to overfill a plurality of openings that have differing widths. Thus, a layer is formed during a <u>first time interval</u> involving a plurality of <u>positive</u> and <u>negative pulses</u>. Thereafter, the thickness of the layer of material (or metal) above the semiconducting substrate is <u>reduced</u> in a <u>second time interval</u> involving a plurality of negative pulses.

It is respectfully submitted that, as amended, all pending claims are allowable over the art of record. The Examiner is invited to contact the undersigned attorney at (713) 934-4055 with any questions, comments or suggestions relating to the referenced patent application.

Respectfully submitted,

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